



### 40V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	Q <sub>g</sub> Typ	I <sub>D</sub> Max T <sub>C</sub> = +25°C (Note 10)
40V	$3m\Omega$ @ $V_{GS} = 10V$	83nC	100A
	$5m\Omega @ V_{GS} = 4.5V$	35nC	100A

### **Features**

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching Ensures More Reliable and Robust End Application
- Low R<sub>DS(ON)</sub> Minimizes Power Losses
- Low Q<sub>g</sub> Minimizes Switching Losses
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

## **Description and Applications**

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

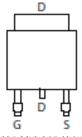
- **Engine Management Systems**
- **Body Control Electronics**
- **DC-DC Converters**
- Motor Control

### **Mechanical Data**

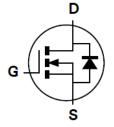
- Case: TO252
- Case Material: Molded Plastic, "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.33 grams (Approximate)



Top View



Pin Out Top View



**Equivalent Circuit** 

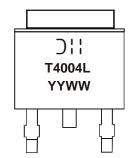
### Ordering Information (Note 5)

Part Number	Case	Packaging
DMTH4004LK3Q-13	TO252	2,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + CI) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product\_compliance\_definitions.html.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**



Oll = Manufacturer's Marking T4004L = Product Type Marking Code YYWW = Date Code Marking YY = Last Digit of Year (ex: 16 = 2016)WW = Week Code (01 to 53)

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## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Drain-Source Voltage	$V_{DSS}$	40	V	
Gate-Source Voltage	$V_{GSS}$	±20	V	
Continuous Drain Current (Note 7) V <sub>GS</sub> = 10V	T <sub>C</sub> = +25°C (Note 10)	I <sub>D</sub>	100	А
, ,	$T_{C} = +100^{\circ}C$		100	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	200	Α	
Maximum Continuous Body Diode Forward Current (Note 7)	I <sub>S</sub>	100	Α	
Avalanche Current, L = 0.2mH		I <sub>AS</sub>	30	Α
Avalanche Energy, L = 0.2mH		E <sub>AS</sub>	90	mJ

# Thermal Characteristics ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 6) $T_A = +25^{\circ}C$		$P_D$	3.9	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{ heta JA}$	38	°C/W	
Total Power Dissipation (Note 7) $T_C = +25^{\circ}C$		$P_D$	180	W
Thermal Resistance, Junction to Case (Note 7)	$R_{\theta JC}$	0.8	°C/W	
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to +175	°C

# **Electrical Characteristics** (@ $T_A = \pm 25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	40	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current, T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_	_	1	μA	$V_{DS} = 32V$ , $V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1	_	3	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance	P-s/s/	_	2.4	3	mΩ	$V_{GS} = 10V, I_D = 50A$	
Static Drain-Source On-Nesistance	R <sub>DS(ON)</sub>	_	4	5	mΩ	$V_{GS} = 4.5V, I_D = 50A$	
Diode Forward Voltage	$V_{SD}$	_	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 50A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C <sub>iss</sub>	_	4,450	_	pF	V 05V V 0V	
Output Capacitance	Coss	_	1,407	_	pF	$V_{DS} = 25V, V_{GS} = 0V,$ - f = 1MHz	
Reverse Transfer Capacitance	Crss	_	74	_	pF	71 = 110102	
Gate Resistance	$R_{g}$	_	0.7	_	$\Omega$ $V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MH$		
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	35	_	nC		
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	83	_	nC	\/ 20\/ I 30\	
Gate-Source Charge	Q <sub>gs</sub>	_	10	_	nC	$V_{DS} = 20V, I_{D} = 30A$	
Gate-Drain Charge	$Q_{gd}$	_	11.2	_	nC		
Turn-On Delay Time	t <sub>D(ON)</sub>	_	5.9	_	ns		
Turn-On Rise Time	t <sub>R</sub>	_	13.2	_	ns	$V_{GS} = 10V, V_{DS} = 20V,$ $R_G = 1.6\Omega, I_D = 30A$	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	25.8	_	ns		
Turn-Off Fall Time	t <sub>F</sub>	_	7.9	_	ns		
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	48	_	ns	I <sub>F</sub> = 50A, di/dt = 100A/µs	
Body Diode Reverse Recovery Charge	$Q_{RR}$	_	72	_	nC	I <sub>F</sub> = 50A, di/dt = 100A/μs	

Notes: 6. Device mounted with exposed drain pad on 25mm by 25mm 2oz copper on a single- sided 1.6mm FR-4 PCB; device is measured under still air conditions while operating in a steady state.

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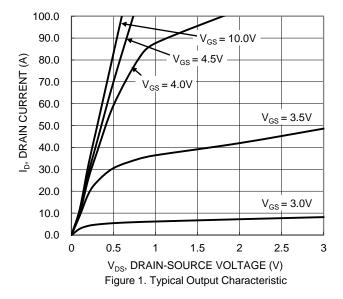
<sup>7.</sup> Thermal resistance from junction to solder point (on the exposed drain pin).

<sup>8.</sup> Short duration pulse test used to minimize self-heating effect.

<sup>9.</sup> Guaranteed by design. Not subject to product testing.

<sup>10.</sup> Package Limited.





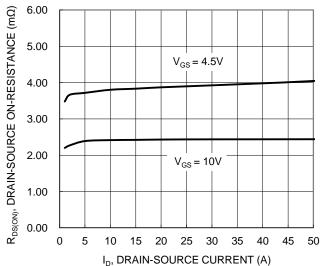


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

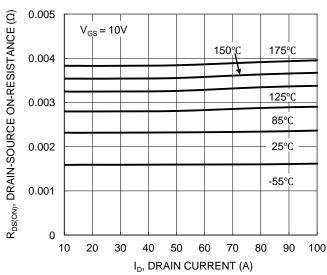
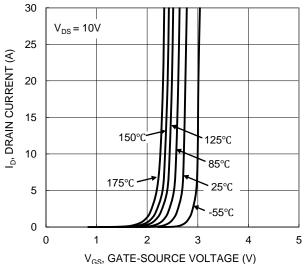


Figure 5. Typical On-Resistance vs. Drain Current and Temperature



V<sub>GS</sub>, GATE-SOURCE VOLTAGE (V) Figure 2. Typical Transfer Characteristic

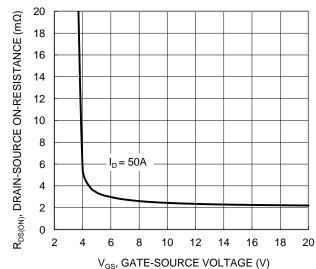


Figure 4. Typical Transfer Characteristic

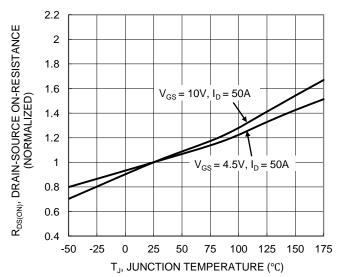


Figure 6. On-Resistance Variation with Temperature



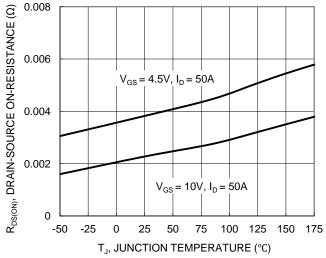


Figure 7. On-Resistance Variation with Temperature

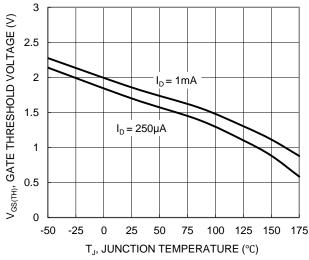


Figure 8. Gate Threshold Variation vs. Temperature

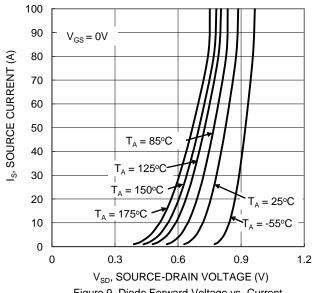
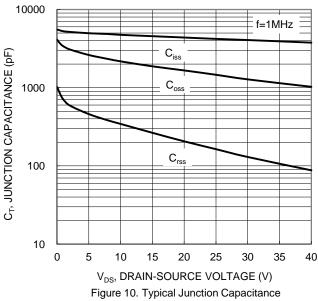


Figure 9. Diode Forward Voltage vs. Current



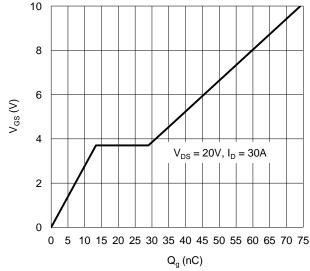


Figure 11. Gate Charge

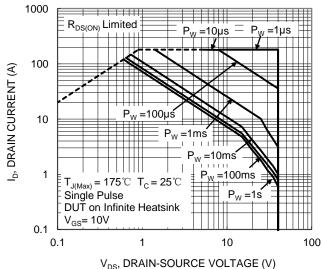


Figure 12. SOA, Safe Operation Area



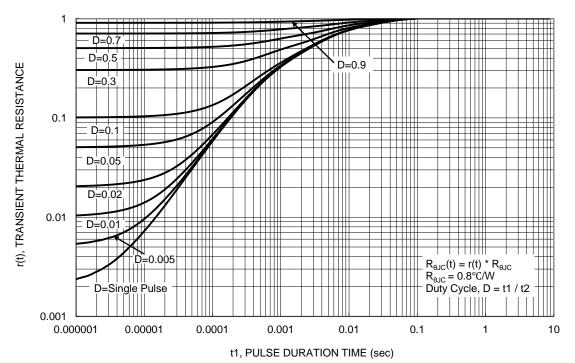


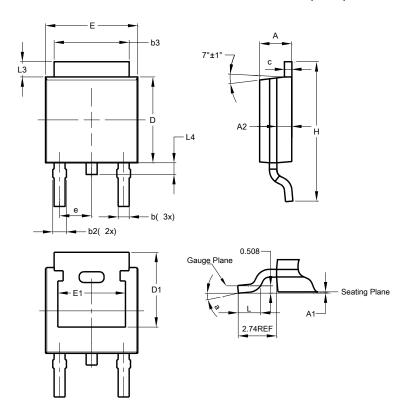
Figure 13. Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### TO252 (DPAK)

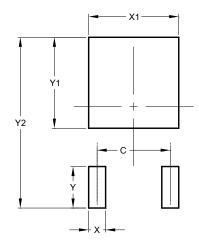


TO252 (DPAK)						
Dim	Min	Max	Тур			
Α	2.19	2.39	2.29			
A1	0.00	0.13	0.08			
A2	0.97	1.17	1.07			
b	0.64	0.88	0.783			
b2	0.76	1.14	0.95			
b3	5.21	5.46	5.33			
С	0.45	0.58	0.531			
D	6.00	6.20	6.10			
D1	5.21	-	-			
е	-	-	2.286			
Е	6.45	6.70	6.58			
E1	4.32	-	-			
Ξ	9.40	10.41	9.91			
L	1.40	1.78	1.59			
L3	0.88	1.27	1.08			
L4	0.64	1.02	0.83			
а	0°	10°	-			
All Dimensions in mm						

# **Suggested Pad Layout**

 $Please see \ http://www.diodes.com/package-outlines.html \ for \ the \ latest \ version.$ 

### TO252 (DPAK)



Dimensions	Value (in mm)		
С	4.572		
Х	1.060		
X1	5.632		
Y	2.600		
Y1	5.700		
Y2	10.700		



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